# 2SC4835

## Silicon NPN epitaxial planar type

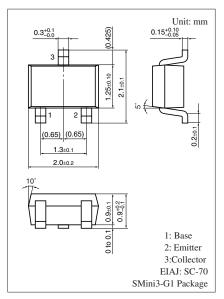
### For UHF band low-noise amplification

### ■ Features

- Low noise figure NF
- High forward transfer gain  $|S_{21e}|^2$
- High transition frequency f<sub>T</sub>
- S-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing

## ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	15	V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	10	V
Emitter-base voltage (Collector open)	$V_{EBO}$	2	V
Collector current	$I_C$	80	mA
Collector power dissipation	P <sub>C</sub>	150	mW
Junction temperature	$T_{j}$	150	°C
Storage temperature	$T_{stg}$	-55 to +150	°C



Marking Symbol: 3M

# $\blacksquare$ Electrical Characteristics $T_a = 25 ^{\circ}C \pm 3 ^{\circ}C$

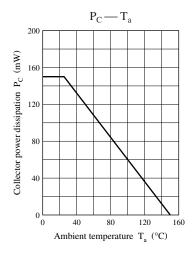
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$I_C = 10 \mu\text{A},  I_E = 0$	15			V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_C = 100 \ \mu A, I_B = 0$	10			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = 10 \text{ V}, I_{E} = 0$			1	μΑ
Emitter-base cutoff current (Collector open)	$I_{EBO}$	$V_{EB} = 2 \text{ V}, I_{C} = 0$			1	μΑ
Forward current transfer ratio *1, 2	h <sub>FE</sub>	$V_{CE} = 8 \text{ V}, I_{C} = 20 \text{ mA}$	50		200	_
Transition frequency	$f_T$	$V_{CE} = 8 \text{ V}, I_{C} = 15 \text{ mA}, f = 800 \text{ MHz}$	5	6		GHz
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = 10 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$		0.7	1.2	pF
(Common base, input open circuited)						
Forward transfer gain	S <sub>21e</sub>   2	$V_{CE} = 8 \text{ V}, I_{C} = 15 \text{ mA}, f = 800 \text{ MHz}$	11	14		dB
Maximum unilateral power gain	$G_{UM}$	$V_{CE} = 8 \text{ V}, I_{C} = 15 \text{ mA}, f = 800 \text{ MHz}$		15		dB
Noise figure	NF	$V_{CE} = 8 \text{ V}, I_{C} = 7 \text{ mA}, f = 800 \text{ MHz}$		1.3	2.0	dB

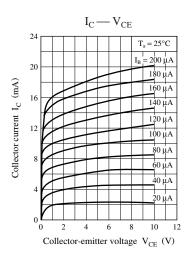
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

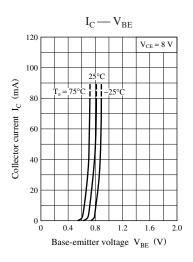
#### 2. \*1: Pulse measurement

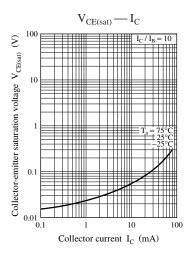
#### \*2: Rank classification

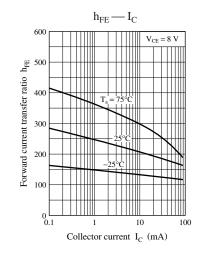
Rank	Q	R	S
$h_{FE}$	50 to 100	80 to 130	100 to 200

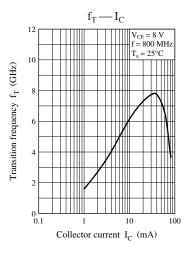


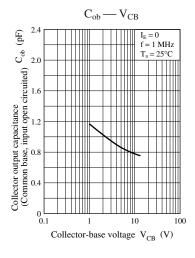


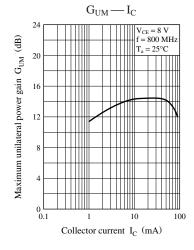


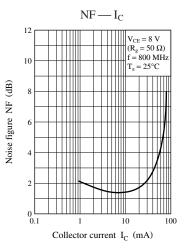












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